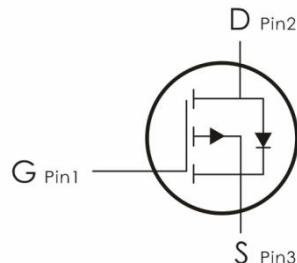
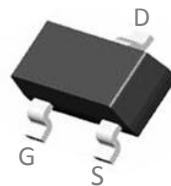


## Description:

This P-Channel MOSFET uses advanced trench technology and design to provide excellent  $R_{DS(on)}$  with low gate charge. It can be used in a wide variety of applications.

## Features:

- 1)  $V_{DS}=-30V, I_D=-4.2A, R_{DS(on)}<52m\Omega @ V_{GS}=-10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra  $R_{DS(on)}$ .
- 5) Excellent package for good heat dissipation.



## Package Marking and Ordering Information:

Part NO.	Marking	Package	Packing
DO3401B	A19T	SOT-23	3000pcs/Reel

## Absolute Maximum Ratings: ( $T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Continuous Drain Current	-4.2	A
$I_{DM}$	Pulse Drain Current Tested <sup>1</sup>	-30	A
$P_D$	Power Dissipation	1.2	W
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

## Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{eJA}$	Thermal Resistance,Junction to Ambient <sup>2</sup>	104	$^\circ C/W$

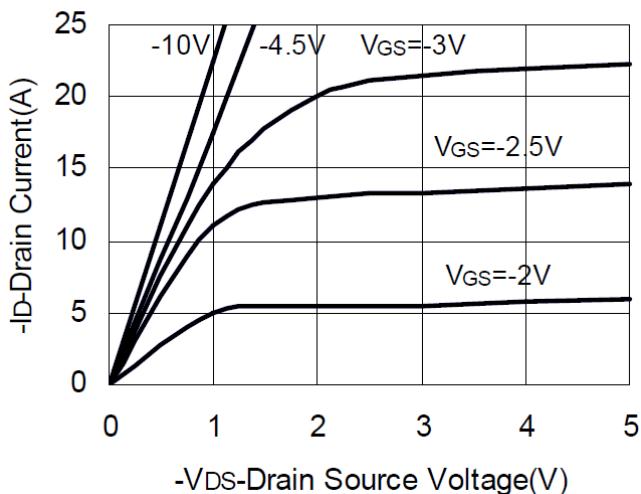
**Electrical Characteristics:** ( $T_A=25^\circ C$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250 \mu A$	-30	---	---	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=-30V$	---	---	-1	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0A$	---	---	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250 \mu A$	-0.6	---	-1.2	V
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=-10V, I_D=-4.3A$	---	40	52	$m \Omega$
		$V_{GS}=-4.5V, I_D=-3.5A$	---	44	60	
		$V_{GS}=-2.5V, I_D=-2.4A$	---	55	72	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=-12V, V_{GS}=0V, f=1MHz$	---	670	---	$pF$
$C_{oss}$	Output Capacitance		---	275	---	
$C_{rss}$	Reverse Transfer Capacitance		---	100	---	
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=-12V, I_D=-4A$	---	9	---	ns
$t_r$	Rise Time		---	15	---	ns
$t_{d(off)}$	Turn-Off Delay Time		---	23	---	ns
$t_f$	Fall Time		---	21	---	ns
$Q_g$	Total Gate Charge	$V_{GS}=-4.5V, V_{DS}=-20V, I_D=-4A$	---	6.2	---	nC
$Q_{gs}$	Gate-Source Charge		---	2.8	---	nC
$Q_{gd}$	Gate-Drain Charge		---	3	---	nC
<b>Drain-Source Diode Characteristics</b>						
$V_{SD}$	Diode forward voltage	$I_S=-1A, V_{GS}=0V$	---	-0.7	-1	V

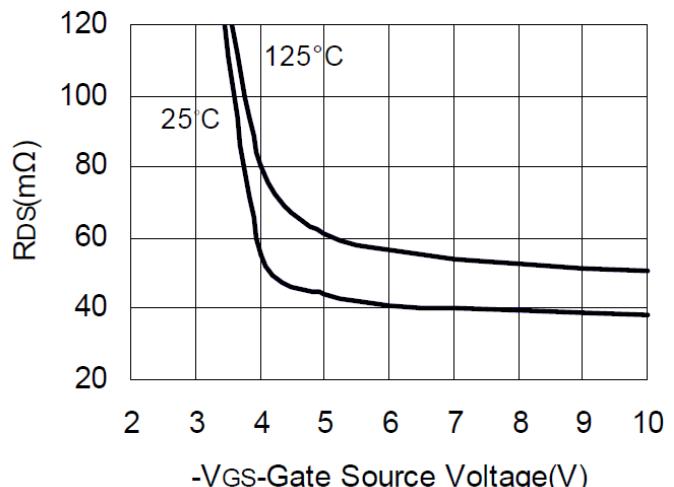
**Notes:**

1. Pulse test: pulse width<=300uS, duty cycle<=2%
2. Static parameters are based on package level with recommended wire bonding

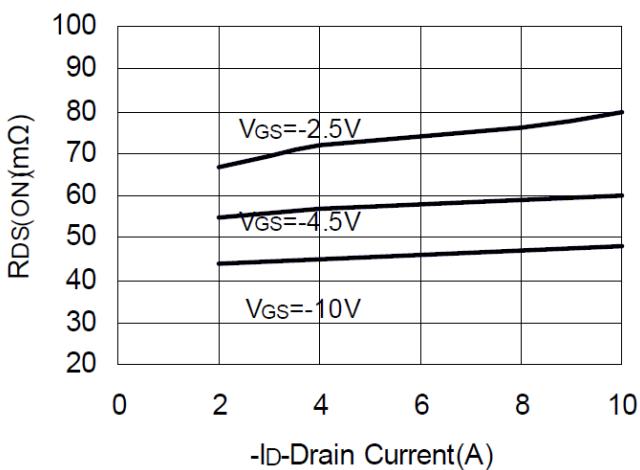
**Typical Characteristics:** ( $T_A=25^\circ\text{C}$  unless otherwise noted)



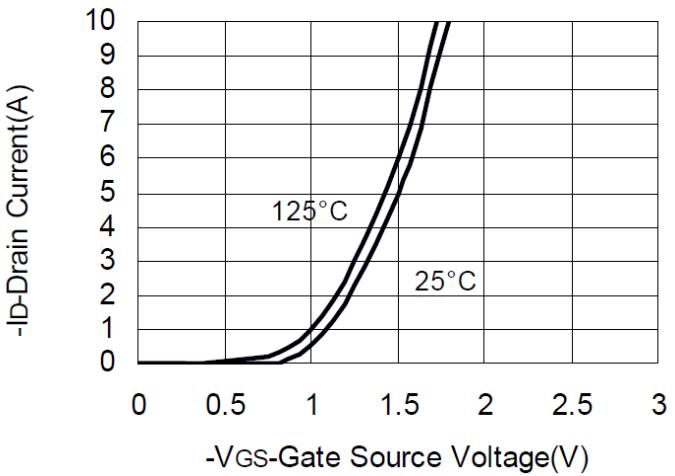
**Fig1. Output Characteristics**



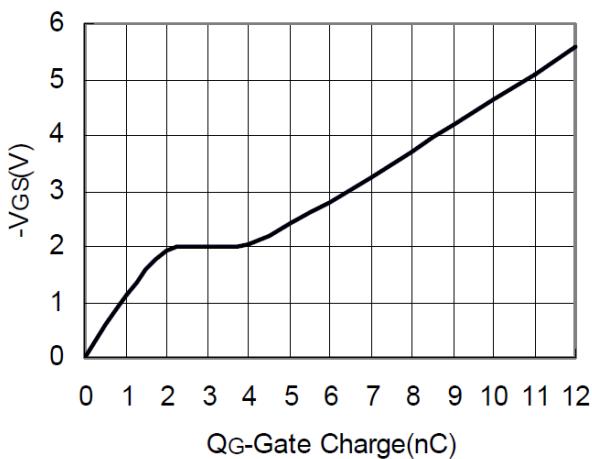
**Fig2. Drain-Source On Resistance**



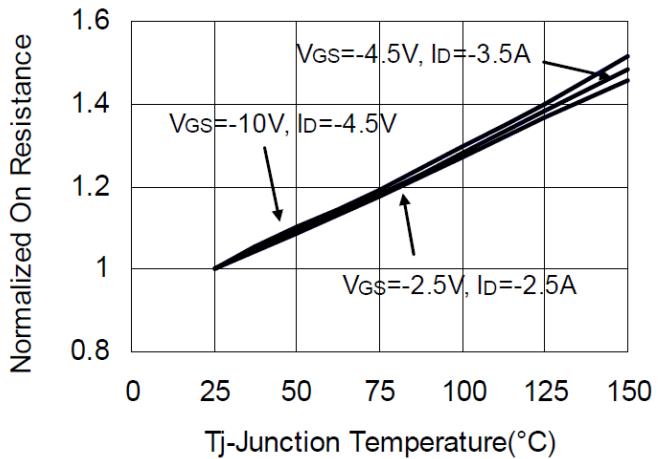
**Fig3. Drain Source On Resistance**



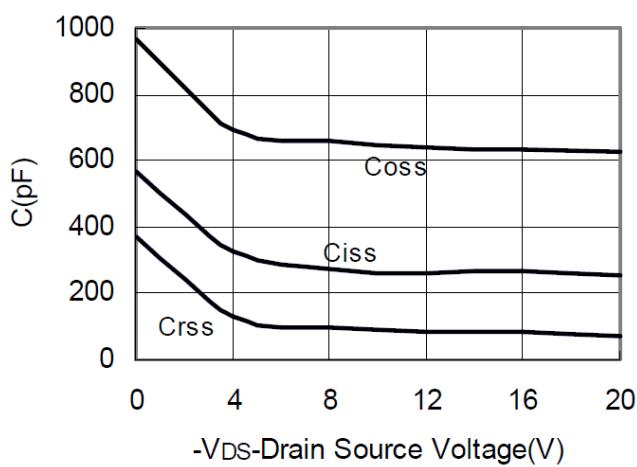
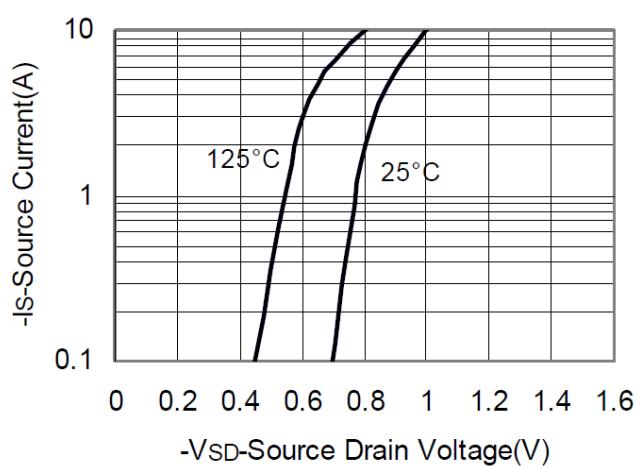
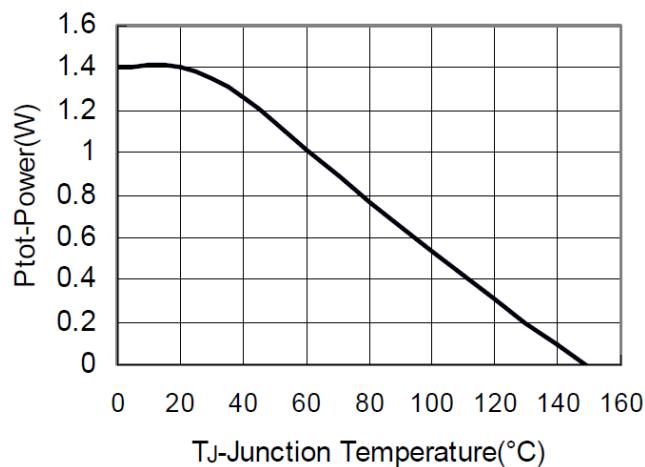
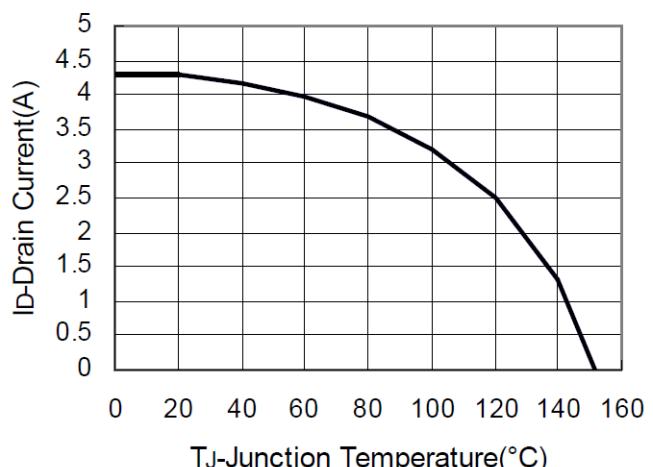
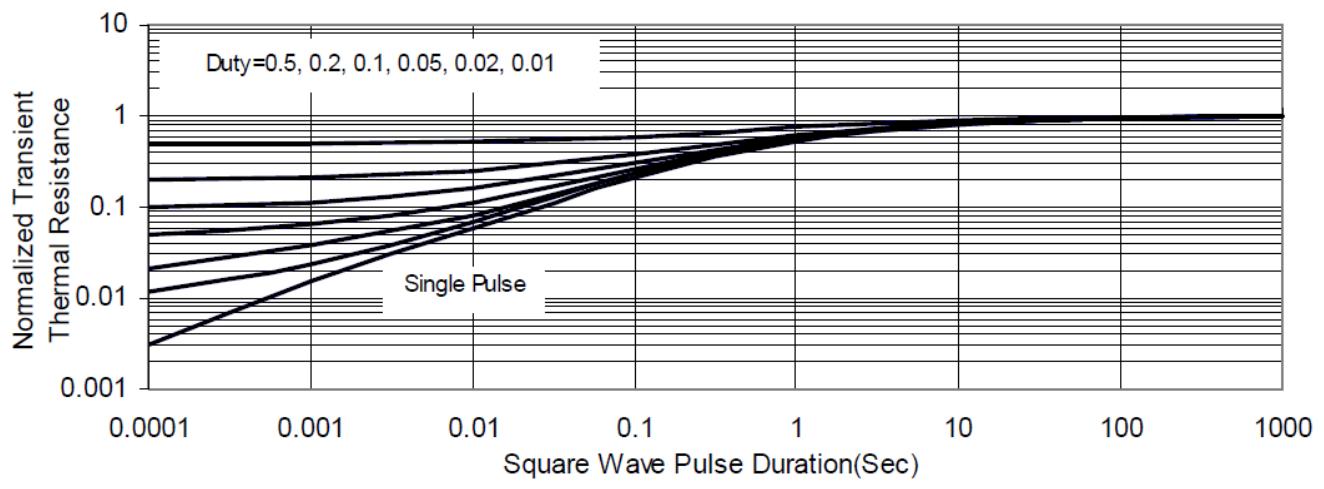
**Fig4. Transfer Characteristics**

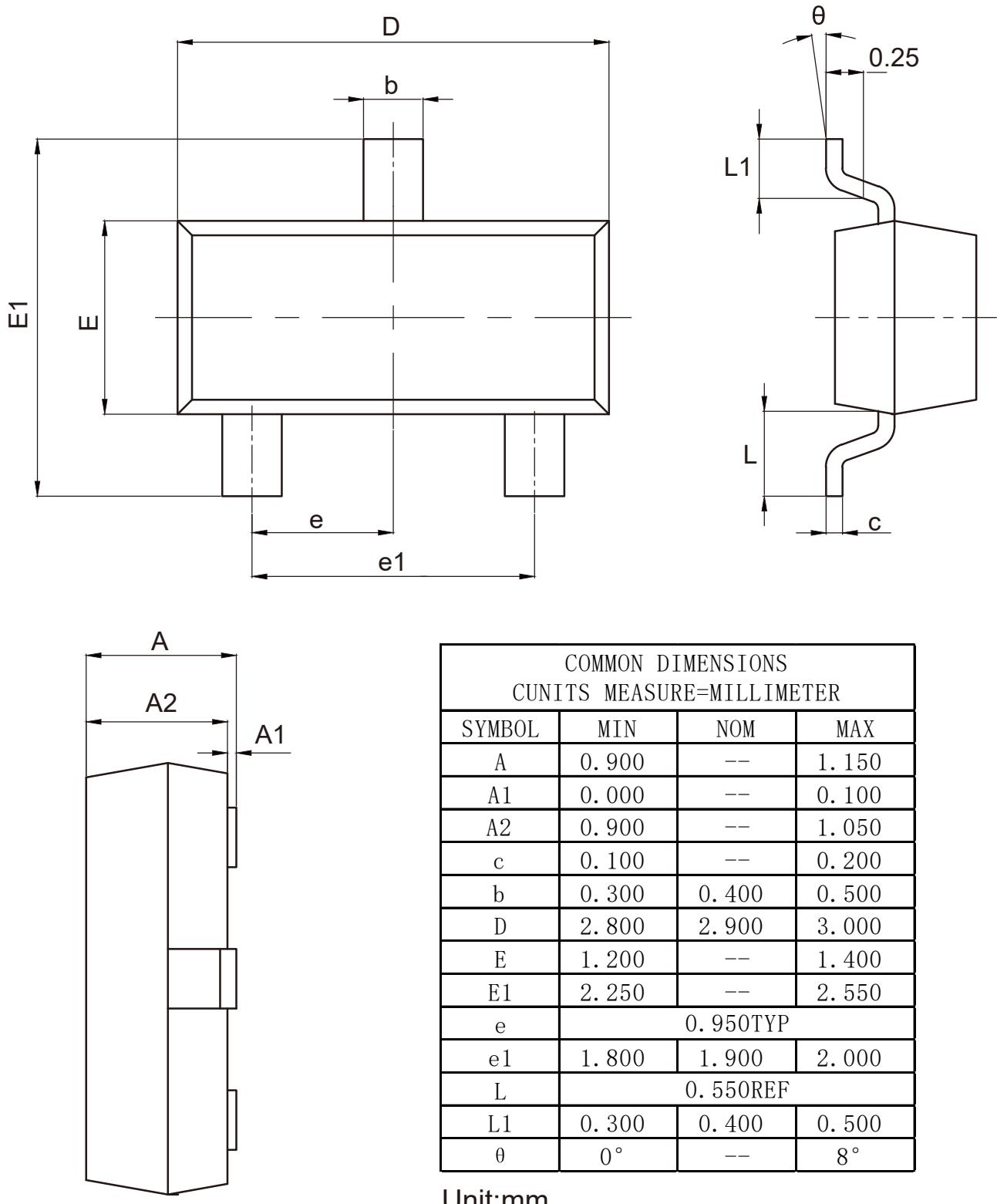


**Fig5. Gate Charge**

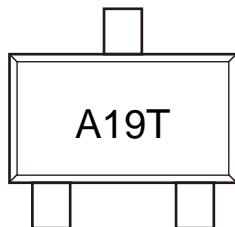


**Fig6. Drain Source Resistance**


**Fig7. Capacitance**

**Fig8. Source Drain Diode Forward**

**Fig9. Power Dissipation**

**Fig10. Drain Current**

**Fig11. Thermal Transient Impedance**

**SOT-23 Package Outline Data**


## Marking Information:



## Previous Version

Version	Date	Subjects (major changes since last revision)
2.0	2024-07-02	<b>Release of final version</b>

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